TL022C, TL022M
DUAL LOW-POWER OPERATIONAL AMPLIFIERS

- **Very Low Power Consumption**
- **Power Dissipation With $\pm$2-V Supplies 170 μW Typ**
- **Low Input Bias and Offset Currents**
- **Output Short-Circuit Protection**
- **Low Input Offset Voltage**
- **Internal Frequency Compensation**
- **Latch-Up-Free Operation**
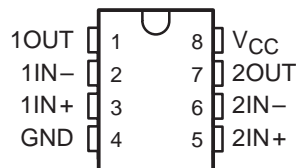- **Popular Dual Operational Amplifier Pinout**

TL022M IS NOT RECOMMENDED FOR NEW DESIGNS

TL022M . . . JG PACKAGE
TL022C . . . D OR P PACKAGE
(TOP VIEW)

```
1OUT  [ 1      8 ]  VCC
1IN−  [ 2      7 ]  2OUT
1IN+  [ 3      6 ]  2IN−
GND   [ 4      5 ]  2IN+
```

TL022M . . . U PACKAGE
(TOP VIEW)

```
NC   [ •1    10 ]  NC
1OUT [ 2      9 ]  VCC+
1IN− [ 3      8 ]  2OUT
1IN+ [ 4      7 ]  2IN−
VCC− [ 5      6 ]  2IN+
```

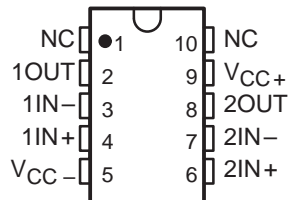## symbol (each amplifier)

description

The TL022 is a dual low-power operational amplifier designed to replace higher power devices in many applications without sacrificing system performance. High input impedance, low supply currents, and low equivalent input noise voltage over a wide range of operating supply voltages result in an extremely versatile operational amplifier for use in a variety of analog applications including battery-operated circuits. Internal frequency compensation, absence of latch-up, high slew rate, and output short-circuit protection assure ease of use.

The TL022C is characterized for operation from 0°C to 70°C. The TL022M is characterized for operation over the full military temperature range of −55°C to 125°C.
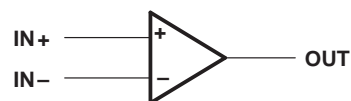
AVAILABLE OPTIONS

T_A	V_{IO}max AT 25°C	PACKAGE			
		SMALL OUTLINE (D)	CERAMIC DIP (JG)	PLASTIC DIP (P)	CERAMIC FLAT PACK (U)
0°C to 70°C	5 mV	TL022CD	—	TL022CP	—
−55°C to 125°C	5 mV	—	TL022MJG	—	TL022MU

The D package is available taped and reeled. Add the suffix R to the device type (i.e. TL022CDR).

TEXAS INSTRUMENTS

TL022C, TL022M
DUAL LOW-POWER OPERATIONAL AMPLIFIERS

schematic
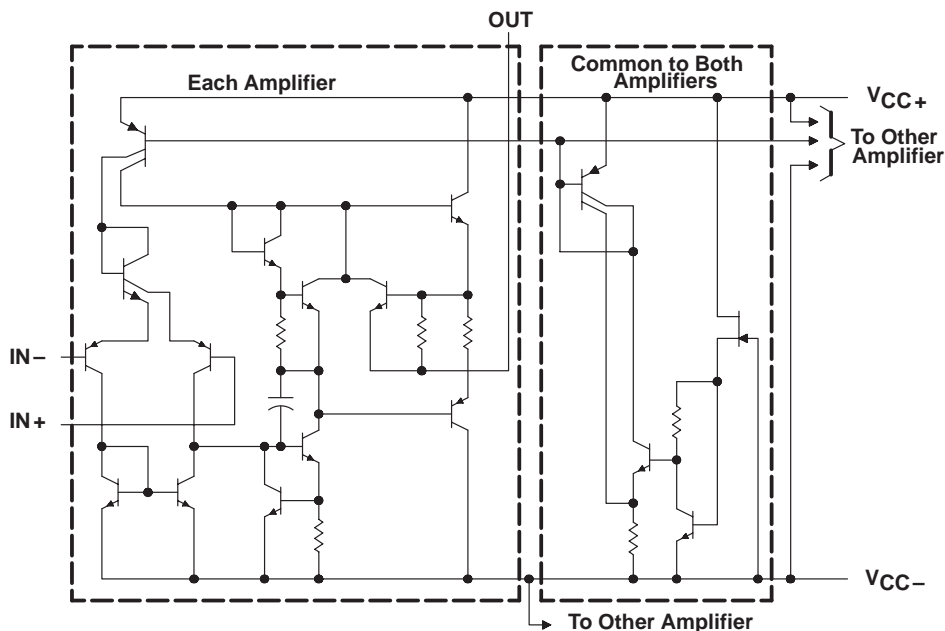
absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

	TL022C	TL022M	UNIT
Supply voltage, V_{CC+} (see Note 1)	18	22	V
Supply voltage, V_{CC-} (see Note 1)	−18	−22	V
Differential input voltage (see Note 2)	±30	±30	V
Input voltage (any input, see Notes 1 and 3)	±15	±15	V
Duration of output short circuit (see Note 4)	unlimited	unlimited	
Continuous total dissipation	See Dissipation Rating Table		
Operating free-air temperature range	0 to 70	−55 to 125	°C
Storage temperature range	−65 to 150	−65 to 150	°C
Lead temperature 1,6 mm (1/16 inch) from case for 60 seconds	JG or U package		300	°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	D or P package	260		°C

NOTES: 1. All voltage values, unless otherwise noted, are with respect to the midpoint between V_{CC+} and V_{CC-}.
2. Differential voltages are at IN+ with respect to IN−.
3. The magnitude of the input voltage must never exceed the magnitude of the supply voltage or 15 V, whichever is less.
4. The output may be shorted to ground or either power supply. For the TL022M only, the unlimited duration of the short circuit applies at (or below) 125°C case temperature or 75°C free-air temperature.

DISSIPATION RATING TABLE

PACKAGE	$T_A \leq 25°C$ POWER RATING	DERATING FACTOR	DERATE ABOVE T_A	$T_A = 70°C$ POWER RATING	$T_A = 125°C$ POWER RATING
D	680 mW	5.8 mW/°C	33°C	464 mW	—
JG	680 mW	8.4 mW/°C	69°C	672 mW	210 mW
P	680 mW	8.0 mW/°C	65°C	640 mW	—
U	675 mW	5.4 mW/°C	25°C	432 mW	135 mW

![Texas Instruments logo]
TEXAS INSTRUMENTS

recommended operating conditions

	MIN	MAX	UNIT
Supply voltage, V_{CC+}	5	15	V
Supply voltage, V_{CC-}	−5	−15	V

electrical characteristics at specified free-air temperature, $V_{CC\pm} = \pm15$ V (unless otherwise noted)

PARAMETER		TEST CONDITIONS†		TL022C			TL022M			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
V_{IO}	Input offset voltage	$V_O = 0$, $R_S = 50\ \Omega$	25°C		1	5		1	5	mV
			Full range			7.5			6	
I_{IO}	Input offset current	$V_O = 0$	25°C		15	80		5	40	nA
			Full range			200			100	
I_{IB}	Input bias current	$V_O = 0$	25°C		100	250		50	100	nA
			Full range			400			250	
V_{ICR}	Common-mode input voltage range		25°C	±12	±13		±12	±13		V
			Full range	±12			±12			
$V_{O(PP)}$	Maximum peak-to-peak output voltage swing	$R_L = 10\ k\Omega$	25°C	20	26		20	26		V
		$R_L \geq 10\ k\Omega$	Full range	20			20			
A_{VD}	Large-signal differehtial voltage amplification	$R_L \geq 10\ k\Omega$, $V_O = \pm10$ V	25°C	60	80		72	86		dB
			Full range	60			66			
B_1	Unity-gain bandwidth		25°C		0.5			0.5		MHz
CMRR	Common-mode rejection ratio	$V_{IC} = V_{ICR}min$, $R_S = 50\ \Omega$	25°C	60	72		60	72		dB
			Full range	60			60			
k_{SVS}	Supply voltage sensitivity ($\Delta V_{IO}/\Delta V_{CC}$)	$V_{CC} = \pm 9$ V to ±15 V, $R_S = 50\ \Omega$	25°C		30	200		30	150	μV/V
			Full range			200			150	
V_n	Equivalent input noise voltage	$A_{VD} = 20$ dB, $B = 1$ Hz, $f = 1$ kHz	25°C		50			50		nV/Hz
I_{OS}	Short-circuit output current		25°C		±6			±6		mA
I_{CC}	Supply current (both amplifiers)	$V_O = 0$, No load	25°C		130	250		130	250	μA
			Full range			250			250	
P_D	Total dissipation (both amplifiers)	$V_O = 0$, No load	25°C		3.9	7.5		3.9	6	mW
			Full range			7.5			6	

† All characteristics are measured under open-loop conditions with zero common-mode input voltage unless otherwise specified. Full range for TL022C is 0°C to 70°C and for TL022M is −55°C to 125°C.

operating characteristics, $V_{CC\pm} = \pm15$ V, $T_A = 25$°C

PARAMETER		TEST CONDITIONS				MIN	TYP	MAX	UNIT
t_r	Rise time	$V_I = 20$ mV,	$R_L = 10\ k\Omega$,	$C_L = 100$ pF,	See Figure 1		0.3		μs
	Overshoot factor						5%		
SR	Slew rate at unity gain	$V_I = 10$ V,	$R_L = 10\ k\Omega$,	$C_L = 100$ pF,	See Figure 1		0.5		V/μs

PARAMETER MEASUREMENT INFORMATION
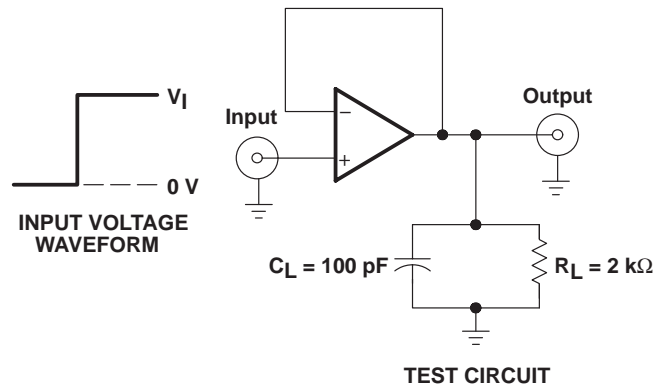
Figure 1. Rise Time, Overshoot Factor, and Slew Rate

TYPICAL CHARACTERISTICS

TOTAL POWER DISSIPATION
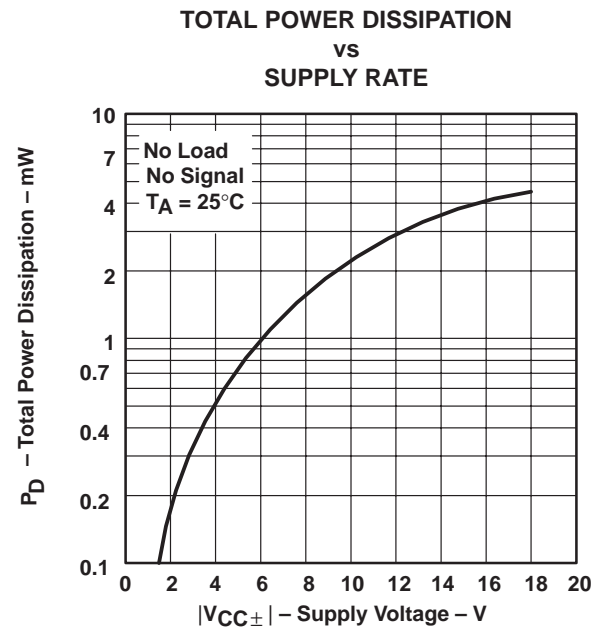**vs**
SUPPLY RATE

Figure 2

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TL022CD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL022C	Samples
TL022CDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL022C	Samples
TL022CDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL022C	Samples
TL022CDG4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL022C	Samples
TL022CDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL022C	Samples
TL022CDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL022C	Samples
TL022CDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL022C	Samples
TL022CDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL022C	Samples
TL022CDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL022C	Samples
TL022CDRG4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	TL022C	Samples
TL022CP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TL022CP	Samples
TL022CP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TL022CP	Samples
TL022CP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TL022CP	Samples
TL022CPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TL022CP	Samples
TL022CPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TL022CP	Samples
TL022CPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	TL022CP	Samples
TL022CPSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	T022	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
TL022CPSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	T022	Samples
TL022CPSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	T022	Samples
TL022CPSRG4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	T022	Samples
TL022CPSRG4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	T022	Samples
TL022CPSRG4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	T022	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE MATERIALS INFORMATION

TAPE AND REEL INFORMATION

REEL DIMENSIONS

TAPE DIMENSIONS

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL022CDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL022CPSR	SO	PS	8	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TL022CDR	SOIC	D	8	2500	340.5	338.1	20.6
TL022CPSR	SO	PS	8	2000	367.0	367.0	38.0

P (R−PDIP−T8)   PLASTIC DUAL−IN−LINE PACKAGE

0.400 (10,16)
0.355 (9,02)

8   5

0.260 (6,60)
0.240 (6,10)

1   4

0.070 (1,78)
0.045 (1,14)

0.045 (1,14)
0.030 (0,76)

0.020 (0,51) MIN

0.200 (5,08) MAX

Seating Plane

0.125 (3,18) MIN

0.100 (2,54)

0.021 (0,53)
0.015 (0,38)

⊕ 0.010 (0,25) Ⓜ

0.325 (8,26)
0.300 (7,62)

0.015 (0,38)

Gauge Plane

0.010 (0,25) NOM

0.430 (10,92)
MAX

4040082/E   04/2010

NOTES: A.   All linear dimensions are in inches (millimeters).
         B.   This drawing is subject to change without notice.
         C.   Falls within JEDEC MS−001 variation BA.

D (R−PDSO−G8)   PLASTIC SMALL OUTLINE

0.197 (5,00)
0.189 (4,80)
/C\

8   5

0.244 (6,20)
0.228 (5,80)

0.157 (4,00)
0.150 (3,80)   /D\

Pin 1
Index Area

1   4

0.050 (1,27)   0.020 (0,51)
                    0.012 (0,31)

⊕ 0.010 (0,25) Ⓜ

0.069 (1,75) Max

0.010 (0,25)
0.004 (0,10)

0.010 (0,25)
0.005 (0,13)

Gauge Plane

⌐ 0.004 (0,10)

Seating Plane

0.010 (0,25)   0°−8°

0.050 (1,27)
0.016 (0,40)

4040047−3/M   06/11

NOTES: A.   All linear dimensions are in inches (millimeters).
          B.   This drawing is subject to change without notice.
       /C\ Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall
             not exceed 0.006 (0,15) each side.
       /D\ Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
          E.   Reference JEDEC MS−012 variation AA.

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D (R−PDSO−G8)   PLASTIC SMALL OUTLINE

Example Board Layout
(Note C)

Stencil Openings
(Note D)

6x1,27

8x0,55

6x1,27

8x1,50

5,40

5,40

Example
Non Soldermask Defined Pad

Example
Pad Geometry
(See Note C)

0,60

1,55

Example
Solder Mask Opening
(See Note E)

0,07

All Around

4211283−2/E   08/12

NOTES: A.   All linear dimensions are in millimeters.
         B.   This drawing is subject to change without notice.
         C.   Publication IPC−7351 is recommended for alternate designs.
         D.   Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should
              contact their board assembly site for stencil design recommendations. Refer to IPC−7525 for other stencil recommendations.
         E.   Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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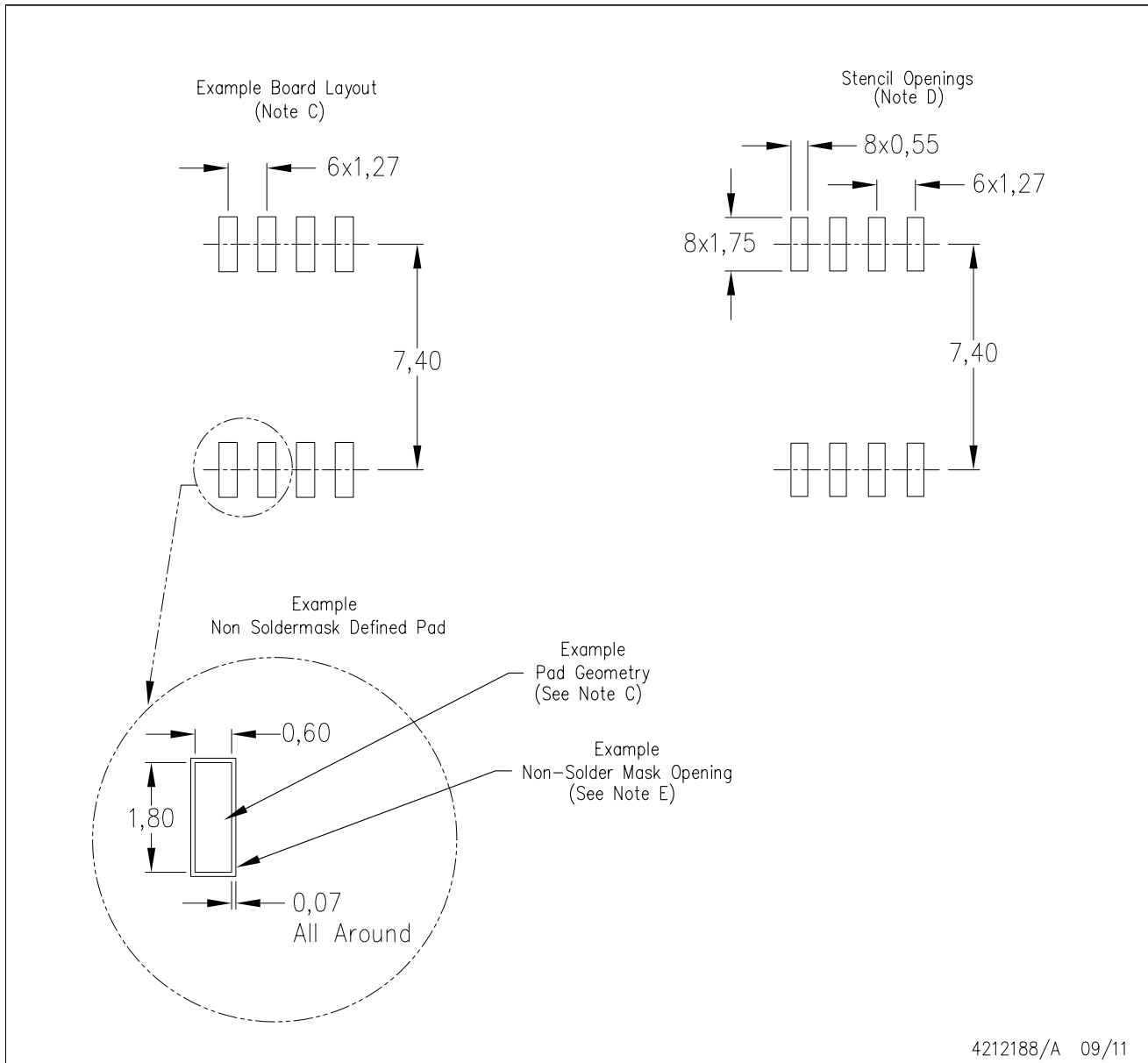INSTRUMENTS
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MECHANICAL DATA

4040063/C 03/03

NOTES: A.   All linear dimensions are in millimeters.
         B.   This drawing is subject to change without notice.
         C.   Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

PS (R-PDSO-G8)   PLASTIC SMALL OUTLINE

Example Board Layout
(Note C)

6x1,27

7,40

Example
Non Soldermask Defined Pad

Stencil Openings
(Note D)

8x0,55

6x1,27

8x1,75

7,40

Example
Pad Geometry
(See Note C)

Example
Non-Solder Mask Opening
(See Note E)

0,60

1,80

0,07
All Around

4212188/A 09/11

NOTES: A.   All linear dimensions are in millimeters.
         B.   This drawing is subject to change without notice.
         C.   Publication IPC-7351 is recommended for alternate designs.
         D.   Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should
              contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
         E.   Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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